

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1. – 13. (Canceled).

14. (Previously presented) A substrate for mounting semiconductor device, comprising:

plural semiconductor-mounting substrate portions, each for mounting a respective semiconductor device,

a connecting portion for connecting said semiconductor-mounting substrate portions : and

a registration mark portion,

wherein each of said semiconductor-mounting substrate portions comprises wirings that

include an external connection terminal and a wire bonding terminal provided in an outer side than said external connection terminal, and

said connecting portion comprises an electrically conductive layer.

15. (Previously presented) A substrate for mounting a semiconductor device according to claim 14, wherein said electrically conductive layer and said wirings are made of the same material.

16. (Previously presented) A substrate for mounting a semiconductor device as claimed in claim 14, wherein nickel and gold are plated on a surface of said wirings.

17. (Previously presented) A substrate for mounting a semiconductor devices as claimed in claim 15, wherein nickel and gold is plated on a surface of said wirings.

18. – 23. (Cancelled).

24. (Previously presented) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said wire bonding terminal is a terminal for connecting a wire from said semiconductor device thereto.

25. (Previously presented) A substrate for mounting a semiconductor device as claimed in claim 24, wherein said external connection terminal is for electrically connecting said substrate to an outer wiring.

26. (Previously presented) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said external connection terminal is for electrically connecting said substrate to an outer wiring.

27. (Currently amended) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said plural semiconductor-mountingsemiconductor mounting substrate portions are side-by-side.

28. (Previously presented) A substrate for mounting a semiconductor device as claimed in claim 14, wherein said plural semiconductor-mounting substrate portions are in a plane.